

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT7309564

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZVI OR-BACH	04/30/2022
BRIAN CRONQUIST	04/29/2022
DEEPAK SEKAR	05/02/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MONOLITHIC 3D INC.
<b>Street Address:</b>	1662 COVE POINT RD
<b>City:</b>	KLAMATH FALLS
<b>State/Country:</b>	OREGON
<b>Postal Code:</b>	97601
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17734867
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	4088399533
<b>Email:</b>	Brian@MonolithIC3D.com
<b>Correspondent Name:</b>	BRIAN CRONQUIST
<b>Address Line 1:</b>	1662 COVE POINT RD
<b>Address Line 4:</b>	KLAMATH FALLS, OREGON 97601
<b>ATTORNEY DOCKET NUMBER:</b>	M3D-15HBVN_40CON4
<b>NAME OF SUBMITTER:</b>	BRIAN CRONQUIST
<b>SIGNATURE:</b>	/Brian Cronquist/
<b>DATE SIGNED:</b>	05/02/2022
<b>Total Attachments: 3</b>	
source=M3D-15HBVN_40con4_Assignment_Zvi---signed#page1.tif	
source=M3D-15HBVN_40con4_Assignment_Brian---signed#page1.tif	
source=M3D-15HBVN_40con4_Assignment_Deepak---signed#page1.tif	

ASSIGNMENT

Whereas, I, **Zvi Or-Bach** (hereinafter referred to as Assignor(s)), residing in Haifa, Israel; have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE**

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about April 29, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

*Zvi Or-Bach*

DATE on 04 / 30 / 2022

(Zvi

Or-Bach)

First Name

Middle Initial

Last Name

ASSIGNMENT

Whereas, I, **Brian Cronquist** (hereinafter referred to as Assignor(s)), residing in **Klamath Falls, Oregon**; have made a certain invention, and United States Patent Application entitled:

**A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE**

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about April 29, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

INVENTOR:

*Brian Cronquist*

DATE on 04 / 29 / 2022

(Brian

Cronquist)

First Name

Middle Initial

Last Name

**ASSIGNMENT**

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and United States Patent Application entitled:

**A 3D SEMICONDUCTOR MEMORY DEVICE AND STRUCTURE**

as described in U.S. Patent Application Serial No. 17/tbd and filed on or about April 29, 2022; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

*Deepak C. Sekar*

DATE on 05 / 02 / 2022

(Deepak		Sekar)
First Name	Middle Initial	Last Name